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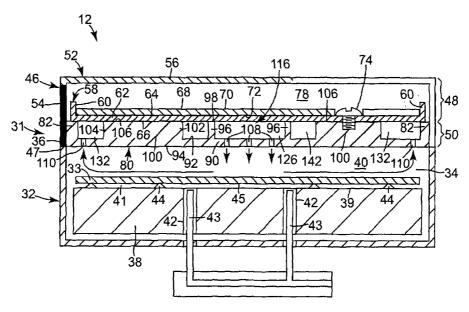
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(54) Title: THERMAL PROCESS STATION WITH HEATED LID



(57) **Abstract:** Methods and apparatuses to improve the temperature uniformity of a workpiece (33) being processed on a heated platen (38) of a thermal processing station (10). A heated platen (38) is enclosed in a housing (31) incorporating an additional heat source (68) that uniformly outputs thermal energy into the process chamber (34) in which the heated platen (38) is positioned. In preferred embodiments, this heat source is positioned in the lid (46) of the housing. It is additionally preferred that the heated lid (46) includes features that provide a gas flow path to introduce to and/or purge gas from the process chamber (34). In terms of photoresist performance, the improved thermal uniformity provided by using such an additional heat source in the housing, e.g., in the lid, offers improved line width control and line uniformity across a wafer.

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According to International Patent Classification (IPC) or to both national classification and IPC B. FIELDS SEARCHED					
Minimum documentation searched (classification system followed by classification symbols) U.S.: 432/250, 253, 258, 247, 237; 118/725, 728; 219/457, 444.1, 390, 405, 443.1; 392/416, 418					
Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched None					
Electronic data base consulted during the international search (name of data base and, where practicable, search terms used) Please See Continuation Sheet					
C. DOC	UMENTS CONSIDERED TO BE RELEVANT				
Category *	Citation of document, with indication, where ap		Relevant to claim No.		
X	US 6,394,797 B1 (SUGAYA et al) 28 May 2002 (28	.05.2002), entire document.	1, 12, 21		
A	US 5,906,683 A (CHEN et al) 25 May 1999 (25.05.1999), entire document.		1-23		
A	US 6,416,318 B1 (LEE et al) 09 July 2002 (09.07.2002), entire document.		1-23		
A	US 6,423,947 B2 (WOMACK et al) 23 July 2002 (23.07.2002), entire document.		1-23		
Α	US 6,600,138 B2 (HAUF et al) 29 July 2003 (29.07.2003), entire document.		1-23		
A	US 6,644,964 B2 (SHIRAKAWA et al) 11 November	1-23			
Further	documents are listed in the continuation of Box C.	See patent family annex.			
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